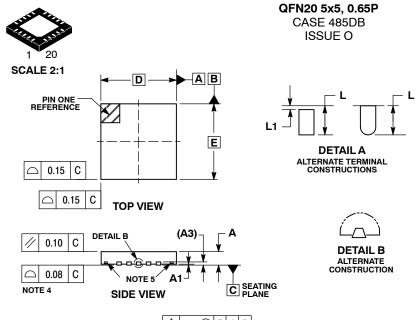
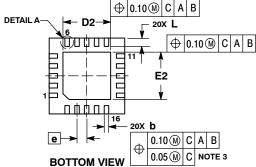
DATE 02 APR 2013





RECOMMENDED SOLDERING FOOTPRINT* 5.30 20X 3.30 0.78 3.30 5.30 PACKAGE OUTLINE 0.65 PITCH 0.40 DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONS AND TOLERANCING PER
- DIMENSIONS AND TOLERANCING PER
 ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.
- OPTIONAL FEATURES.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1		0.05	
А3	0.20 REF		
b	0.25	0.35	
D	5.00 BSC		
D2	3.05	3.25	
Е	5.00 BSC		
E2	3.05	3.25	
е	0.65 BSC		
L	0.45	0.65	
L1		0.15	

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

Α

= Wafer Lot WL YY = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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